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Understanding Embedded - Microcontroller, Microprocessor, FPGA Modules

Embedded - Microcontroller, Microprocessor, and FPGA Modules are fundamental components in modern electronic systems, offering a wide range of functionalities and capabilities. Microcontrollers are compact integrated circuits designed to execute specific control tasks within an embedded system. They typically include a processor, memory, and input/output peripherals on a single chip. Microprocessors, on the other hand, are more powerful processing units used in complex computing tasks, often requiring external memory and peripherals. FPGAs (Field Programmable Gate Arrays) are highly flexible devices that can be configured by the user to perform specific logic functions, making them invaluable in applications requiring customization and adaptability.

Applications of Embedded - Microcontroller,

Details	
Product Status	Obsolete
Module/Board Type	MCU, FPGA
Core Processor	ARM® Cortex®-A9
Co-Processor	Zynq-7000 (Z-7035)
Speed	-
Flash Size	32MB
RAM Size	1GB
Connector Type	Samtec UFPS
Size / Dimension	2.05" x 2.99" (52mm x 76mm)
Operating Temperature	0°C ~ 70°C
Purchase URL	https://www.e-xfl.com/product-detail/trenz-electronic/te0745-02-35-1ca

2.2 Block Diagram

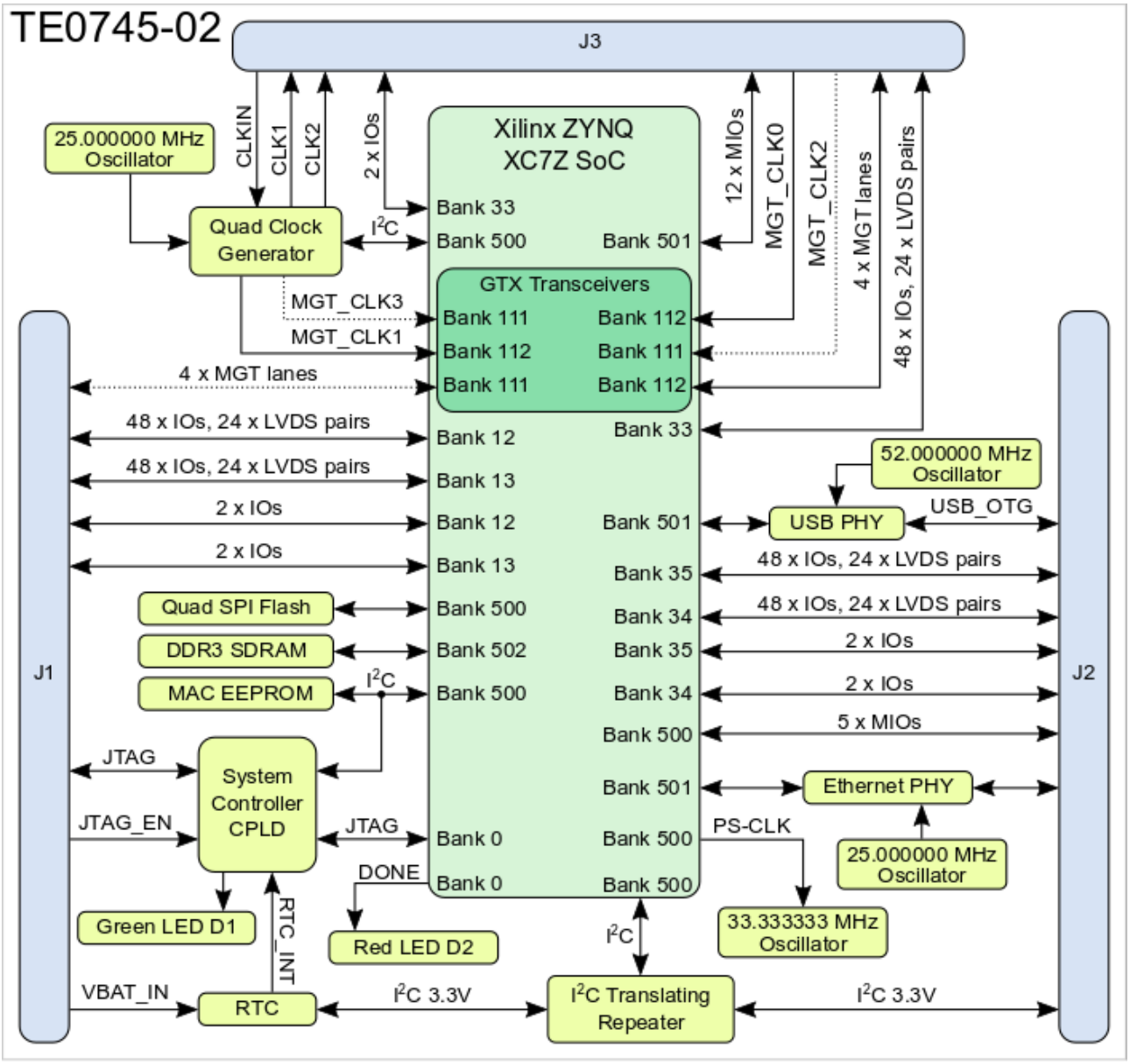

Figure 1: TE0745-02 Block Diagram.

2.3 Main Components

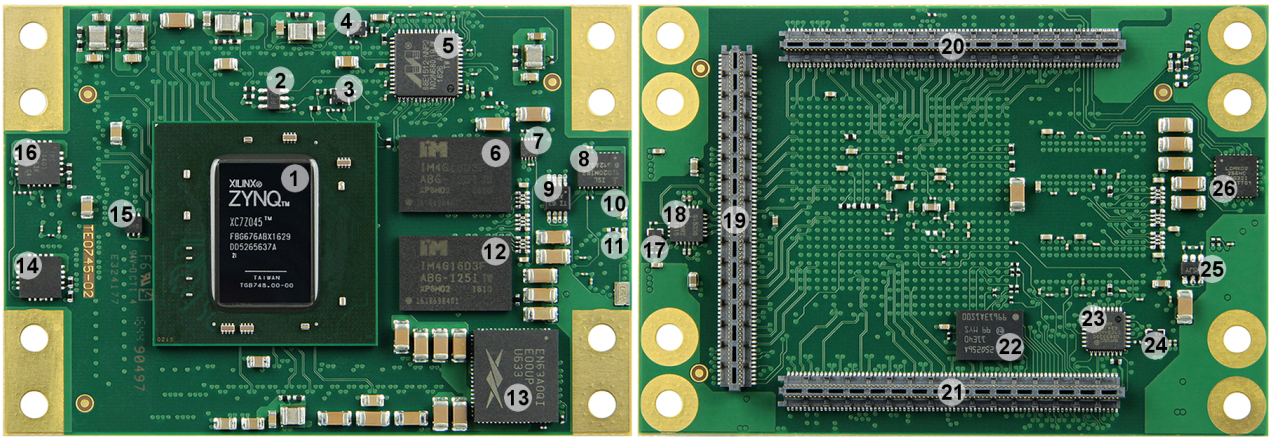

Figure 2: TE0745-02 SoC module.

1. Xilinx Zynq XC7Z family SoC, U1
2. 256 Mbit Quad SPI Flash memory Micron N25Q256A, U12
3. Reference clock signal oscillator SiTime SiT8008BI @33.333333 MHz, U12
4. Reference clock signal oscillator SiTime SiT8008BI @25.000000 MHz, U9
5. Marvell Alaska 88E1512 Gigabit Ethernet PHY, U3
6. Intelligent Memory 512 MByte DDR3L-1600 SDRAM (8 Banks a 32 MWords, 16-bit word width), U3
7. TI TPS51206 DDR3 memory termination regulator with buffered reference voltage VTTREF, U18
8. Intersil ISL12020MIRZ Real-Time-Clock, U24
9. TI TCA9517 level-shifting I^2C bus repeater, U17
10. Red LED, D2
11. Green LED, D1
12. Intelligent Memory 512 MByte DDR3L-1600 SDRAM (8 banks a 32 MWords, 16 Bit word width), U5
13. Altera Enpirion EN63A0QI 12A DC-DC PowerSoC @1.0V (VCCINT), U4
14. TI TPS74401RGW LDO DC-DC regulator @1.2V (MGTAVTT), U8
15. TI TPS72018DRVR LDO DC-DC regulator @1.8V (MGTAUX), U6
16. TI TPS74401RGW LDO DC-DC regulator @1.0V (MGTAVCC), U11
17. Silicon Labs Si5338A I^2C Programmable Quad Clock Generator, U13
18. Reference clock signal oscillator SiTime SiT8008BI @25.000 MHz, U21
19. Samtec ST5-80-1.50-L-D-P-TR 160-pin stacking strips (2 rows a 80 positions), J3
20. Samtec ST5-80-1.50-L-D-P-TR 160-pin stacking strips (2 rows a 80 positions), J1
21. Samtec ST5-80-1.50-L-D-P-TR 160-pin stacking strips (2 rows a 80 positions), J2
22. 256 Mbit Quad SPI Flash memory (Micron N25Q256A), U14
23. Microchip USB3320 USB transceiver PHY , U32
24. Reference clock signal oscillator SiTime SiT8008BI @52.000000 MHz, U33
25. Microchip 24AA025E48 EEPROM for MAC address, U23
26. Lattice Semiconductor MachXO2-256HC System Controller CPLD, U2

2.4 Initial Delivery State

Storage Device Name	Content	Notes
24AA025E48 EEPROM	User content, not programmed	Valid MAC Address from manufacturer.

Storage Device Name	Content	Notes
SPI Flash OTP Area	Empty, not programmed	Except serial number programmed by flash vendor.
SPI Flash Quad Enable bit	Programmed	-
SPI Flash main array	Not programmed	-
eFUSE USER	Not programmed	-
eFUSE Security	Not programmed	-
Si5338 OTP NVM	Not programmed	OTP not re-programmable after delivery from factory

Table 1: Initial delivery state.

Lane	Bank	Type	Signal Name	B2B Pin	FPGA Pin
0	112	GTX	• MGT_RX0_P • MGT_RX0_N • MGT_TX0_P • MGT_TX0_N	• J3-50 • J3-52 • J3-51 • J3-53	• MGTHRXP0_112, AB4 • MGTHRXN0_112, AB3 • MGTHTXP0_112, AA2 • MGTHTXN0_112, AA1
1	112	GTX	• MGT_RX1_P • MGT_RX1_N • MGT_TX1_P • MGT_TX1_N	• J3-56 • J3-58 • J3-57 • J3-59	• MGTHRXP1_112, Y4 • MGTHRXN1_112, Y3 • MGTHTXP1_112, W2 • MGTHTXN1_112, W1
2	112	GTX	• MGT_RX2_P • MGT_RX2_N • MGT_TX2_P • MGT_TX2_N	• J3-62 • J3-64 • J3-63 • J3-65	• MGTHRXP2_112, V4 • MGTHRXN2_112, V3 • MGTHTXP2_112, U2 • MGTHTXN2_112, U1
3	112	GTX	• MGT_RX3_P • MGT_RX3_N • MGT_TX3_P • MGT_TX3_N	• J3-68 • J3-70 • J3-69 • J3-71	• MGTHRXP3_112, T4 • MGTHRXN3_112, T3 • MGTHTXP3_112, R2 • MGTHTXN3_112, R1
4	111 [1)]	GTX	• MGT_RX4_P • MGT_RX4_N • MGT_TX4_P • MGT_TX4_N	• J1-23 • J1-21 • J1-22 • J1-20	• MGTHRXP0_111, AD8 • MGTHRXN0_111, AD7 • MGTHTXP0_111, AF8 • MGTHTXN0_111, AF7
5	111 [1)]	GTX	• MGT_RX5_P • MGT_RX5_N • MGT_TX5_P • MGT_TX5_N	• J1-17 • J1-15 • J1-16 • J1-14	• MGTHRXP1_111, AE6 • MGTHRXN1_111, AE5 • MGTHTXP1_111, AF4 • MGTHTXN1_111, AF3
6	111 [1)]	GTX	• MGT_RX6_P • MGT_RX6_N • MGT_TX6_P • MGT_TX6_N	• J1-11 • J1-9 • J1-10 • J1-8	• MGTHRXP2_111, AC6 • MGTHRXN2_111, AC5 • MGTHTXP2_111, AE2 • MGTHTXN2_111, AE1
7	111 [1)]	GTX	• MGT_RX7_P • MGT_RX7_N • MGT_TX7_P • MGT_TX7_N	• J1-5 • J1-3 • J1-4 • J1-2	• MGTHRXP3_111, AD4 • MGTHRXN3_111, AD3 • MGTHTXP3_111, AC2 • MGTHTXN3_111, AC1

Table 3: SoC's MGT lanes connections to the B2B connectors.

Below are listed MGT banks reference clock sources.

Clock signal	Bank	Source	FPGA Pin	Notes
MGT_CLK0_P	112	B2B, J3-75	MGTREFCLK0P_112, R6	Supplied by the carrier board.
MGT_CLK0_N	112	B2B, J3-77	MGTREFCLK0N_112, R5	Supplied by the carrier board.
MGT_CLK1_P	112	U16, CLK0A	MGTREFCLK1P_112, U6	On-module Si5338A.
MGT_CLK1_N	112	U16, CLK0B	MGTREFCLK1N_112, U5	On-module Si5338A.
MGT_CLK2_P	111 [1)]	B2B, J3-81	MGTREFCLK0P_111, W6	Supplied by the carrier board.
MGT_CLK2_N	111 [1)]	B2B, J3-83	MGTREFCLK0N_111, W5	Supplied by the carrier board.
MGT_CLK3_P	111 [1)]	U16, CLK3A	MGTREFCLK1P_111, AA6	On-module Si5338A.
MGT_CLK3_N	111 [1)]	U16, CLK3B	MGTREFCLK1N_111, AA5	On-module Si5338A.

Pin Name	Mode	Function	B2B Connector Pin	Default Configuration
MIO8	Input	PS MIO	-	User I/O (pulled-up to PS_1.8V).
MIO0	Input	PS MIO	J2-137	User I/O.
RTC_INT	Input	Interrupt signal	-	Interrupt-signal from on-board RTC.
LED	Output	LED control	-	Green LED D1, indicates SC-CPLD activity by blinking.

Table 6: System Controller CPLD special purpose I/O pins.

3.5 Quad SPI Interface

Quad SPI Flash (U14) is connected to the Zynq PS QSPI0 interface via PS MIO bank 500, pins MIO1 ... MIO6.

MIO	Signal Name	U14 Pin
1	SPI-CS	C2
2	SPI-DQ0/M0	D3
3	SPI-DQ1/M1	D2
4	SPI-DQ2/M2	C4
5	SPI-DQ3/M3	D4
6	SPI-SCK/M4	B2

Table 7: MIO-pin assignment of the Quad SPI Flash memory IC.

3.6 Gigabit Ethernet Interface

On-board Gigabit Ethernet PHY (U7) is provided with Marvell Alaska 88E1512 IC. The Ethernet PHY RGMII interface is connected to the Zynq Ethernet0 PS GEM0. I/O voltage is fixed at 1.8V for HSTL signaling. The reference clock input of the PHY is supplied from the on-board 25.000000 MHz oscillator (U9). The 125MHz PHY output clock (PHY_CLK125M) is routed to the B2B connector J2 pin 150.

PHY Pin	ZYNQ PS	B2B	Notes
MDC/MDIO	MIO52, MIO53	-	-
PHY LEDs	-	PHY_LED0: J2-144 PHY_LED1: J2-146	-
PHY_LED2 / INTn:	-	J2-148	Active low interrupt line.
PHY_CLK125M	-	J2-150	125 MHz Ethernet PHY clock out.
CONFIG	-	-	Permanent logic high.
RESETn	MIO9	-	Active low reset line.
RGMII	MIO16 ... MIO27	-	Reduced Gigabit Media Independent Interface.

The schematics for the USB connector and required components is different depending on the USB usage. USB standard A or B connectors can be used for Host or Device modes. A Mini USB connector can be used for USB Device mode. A USB Micro connector can be used for Device mode, OTG Mode or Host Mode.

3.8 I2C Interface

The I^2C interface on B2B connector J2 has PS_3.3V as reference voltage and is connected to the Zynq SoC via voltage level translating (3.3V ↔ 1.8V) I^2C bus repeater (U17).:

B2B pin	Signal Schematic Name	Notes
J2-119	I2C_33_SCL	3.3V reference voltage
J2-121	I2C_33_SDA	3.3V reference voltage

Table 10: Pin assignment of the B2B I^2C interface.

The on-module I^2C interface works with reference voltage 1.8V:

PS Bank 500	Signal Schematic Name	Notes
MIO 10	I2C_SCL	1.8V reference voltage
MIO 11	I2C_SDA	1.8V reference voltage

Table 11: MIO-pin assignment of the on-module I^2C interface.

Except the on-module RTC (U24), all other on-module I^2C slave devices are operating with the reference voltage PS_1.8V.

I^2C addresses for on-module devices are listed in the table below:

I2C Device	I2C Address	Notes
Zynq chip U1, bank 500 (PS MIO), pins MIO10 (SCL), MIO11 (SDA)	User programmable.	Configured as I^2C by default.
Quad programmable PLL clock generator U16: pins 12 (SCL), 19 (SDA)	0x70	-
MAC Address EEPROM U23, pins 1 (SCL), 3 (SDA)	0x53	-
SC CPLD U2, bank 2, pins 16 (SDA), 17 (SCL)	User programmable.	-
RTC, U24	0x6F	-
RTC RAM, U24	0x57	-

Table 12: Module's I^2C-interfaces overview.

4 Boot Process

TE0745 module supports different boot modes which are configurable by the control line 'BOOTMODE' and 'BOOTMODE_1'. The line 'BOOTMODE' is available on B2B connector pin J2-133, the line 'BOOTMODE_1' is connected to the System Controller CPLD on bank 1, pin 21 (permanent logic high in standard SC-CPLD firmware).The boot mode selection will be set by the Zynq's PS MIO pins MIO3...MIO5.

Following table describes how to set the control lines to configure the boot mode:

Boot Mode	MIO5 (BOOTMODE_1), SC CPLD	MIO4 (BOOTMODE), J2-133	Note
JTAG	0	0	-
QSPI Flash Memory	1	0	standard mode in current configuration.
SD-Card	1	1	SD-Card on base board necessary.

Table 13: Selectable boot modes.

In delivery state of the SoM the boot mode depends on the configured SC-CPLD firmware. Basically MIO5 is set to 1 and JTAG is in cascade.

5.6 RTC - Real Time Clock

An temperature compensated Intersil ISL12020M is used as Real Time Clock (U24). Battery voltage must be supplied to the clock from the base board via pin 'VBAT_IN' (J1-146). Battery backed registers can be accessed over I^2C bus at slave address 0x6F. General purpose RAM of the RTC can be accessed at I^2C slave address 0x57. RTC IC is supported by Linux so it can be used as hwclock device. The interrupt line 'RTC_INT' of the RTC is connected to System Controller CPLD bank 3 pin 4.

5.7 Programmable PLL Clock (Phase-Locked Loop)

There is a Silicon Labs I^2C programmable quad PLL clock generator Si5338A (U16) on-board. It's output frequencies can be programmed by using the I^2C-bus with address 0x70.

A 25 MHz (U21) oscillator is connected to pin 3 (IN3) and is used to generate the output clocks.

Once running, the frequency and other parameters can be changed by programming the device using the I^2C-bus connected between the Zynq module (master) and reference clock signal generator (slave).

Si5338A Pin	Signal Name / Description	Connected To	Direction	Note
IN1	CLKIN_P	B2B, J3-76	Input	Reference input clock from base board.
IN2	CLKIN_N	B2B, J3-74	Input	
IN3	Reference input clock.	Oscillator U21, pin 3	Input	25.000000 MHz oscillator, Si8008BI.
IN4	-	GND	Input	I^2C slave device address LSB (0x70 default address).
IN5	-	Not connected.	Input	Not used.
IN6	-	GND	Input	Not used.
CLK0A	MGT_CLK1_P	Zynq Soc U1, pin U6	Output	MGT bank 112 reference clock.
CLK0B	MGT_CLK1_N	Zynq Soc U1, pin U5	Output	
CLK1A	CLK1_P	B2B, J3-80	Output	Reference clock output to base board.
CLK1B	CLK1_N	B2B, J3-82	Output	
CLK2A	CLK2_P	B2B, J3-86	Output	Reference clock output to base board.
CLK2B	CLK2_P	B2B, J3-88	Output	
CLK3A	MGT_CLK3_P	Zynq Soc U1, pin AA6	Output	MGT bank 111 reference clock.
CLK3B	MGT_CLK3_N	Zynq Soc U1, pin AA6	Output	

Table 14: Programmable quad PLL clock generator inputs and outputs.

5.8 Oscillators

The SoC module has following reference clocking signals provided by external baseboard sources and on-board oscillators:

Clock Source	Schematic Name	Frequency	Clock Input Destination
SiTime SiT8008BI oscillator, U21	-	25.000000 MHz	Quad PLL clock generator U16, pin 3
SiTime SiT8008BI oscillator, U12	PS_CLK	33.333333 MHz	Bank 500 (MIO0 bank), pin B24
SiTime SiT8008BI oscillator, U33	OTG-RCLK	52.000000 MHz	USB 2.0 transceiver PHY U32, pin 26
SiTime SiT8008BI oscillator, U9	ETH_CLKIN	25.000000 MHz	Gigabit Ethernet PHY U7, pin 34

Table 15: Clock sources overview.

5.9 On-board LEDs

LED	Color	Connected to	Description and Notes
D1	Green	System Controller CPLD, bank 3, pin 5	System main status LED, blinking indicates system activity
D2	Red	Zynq chip (U1), bank 0 (config bank), 'DONE' (pin W9)	Reflects inverted DONE signal. ON when FPGA is not configured, OFF as soon as PL is configured. This LED remains OFF if System Controller CPLD can not power up the PL supply voltage.

Table 16: LEDs of the module.

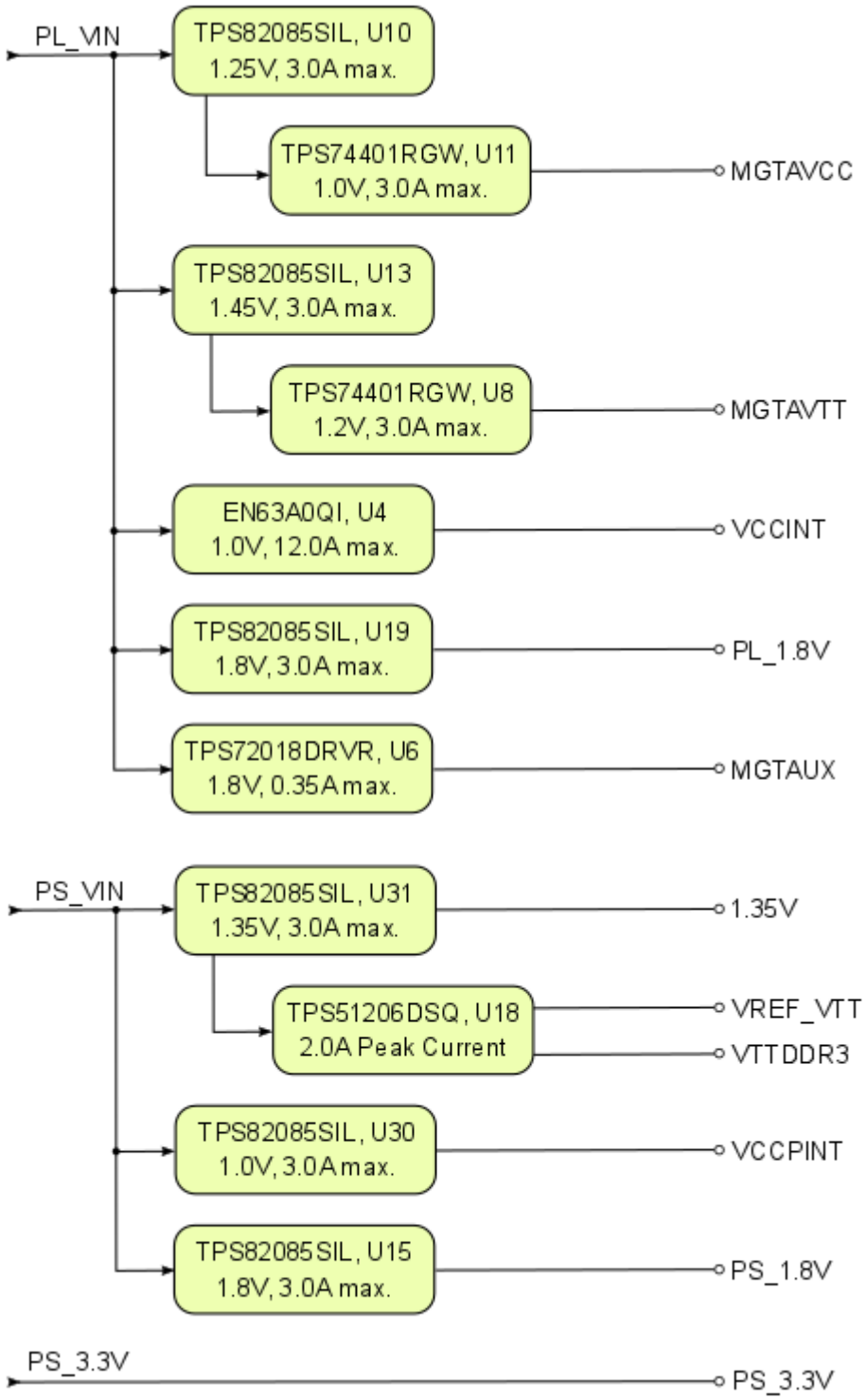

Figure 3: Power Distribution Diagram

See Xilinx data sheet DS191 for additional information. User should also check related base board documentation when intending base board design for TE0745 module.

⚠ Current rating of Samtec Razor Beam LP Terminal/Socket Strip ST5/SS5 B2B connectors is 1.5 A per pin (1 pin powered per row).

6.3 Power-On Sequence Diagram

The TE0745 SoM meets the recommended criteria to power up the Xilinx Zynq MPSoC properly by keeping a specific sequence of enabling the on-board DCDC converters dedicated to the particular functional units of the Zynq chip and powering up the on-board voltages.

Following diagram clarifies the sequence of enabling the particular on-board voltages, which will power-up in descending order as listed in the blocks of the diagram:

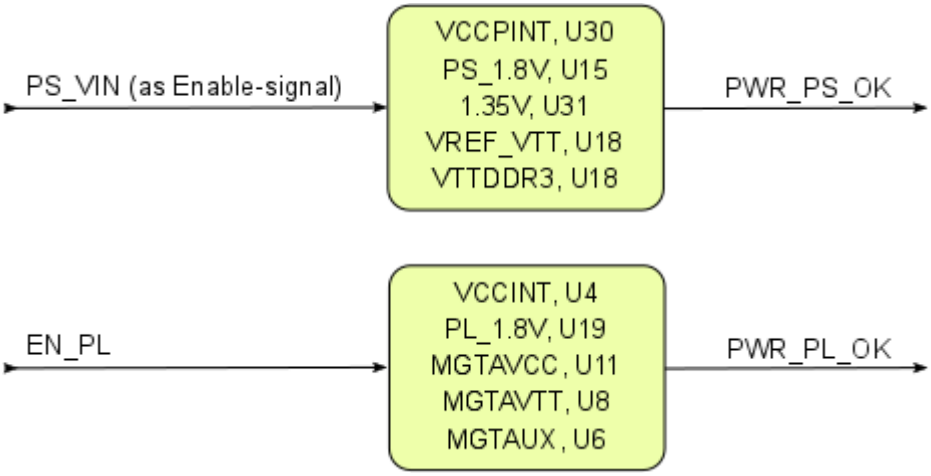

Figure 4: Power-On Sequence

The Enable-Signal 'EN_PL' is permanently logic high in standard SC-CPLD firmware. The "Power Good"-signals 'PWR_PS_OK' and 'PWR_PL_OK' (latter low-active, extern pull-up needed) are available B2B-connector J2 (pins J2-139, J2-135) and on the SC-CPLD.

6.4 Voltage Monitor Circuit

The voltages 'VCCPINT' and 'PS_1.8V' are monitored by the voltage monitor circuit U41, which generates the POR_B reset signal at Power-On. A manual reset is also possible by driving the MR-pin (available on J2-131 or SC-CPLD) to GND. Leave this pin unconnected or connect to VDD (PS_1.8V) when unused.

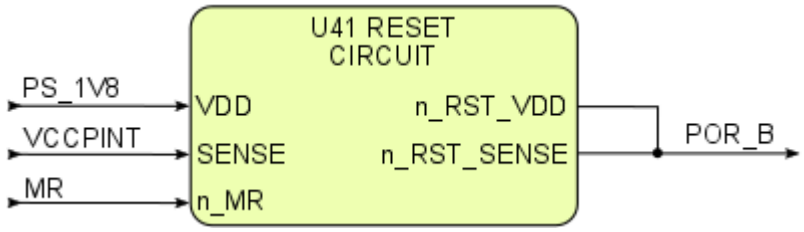

Figure 5: Voltage monitor circuit.

6.5 Power Rails

Voltages on B2B Connectors	B2B J1 Pin	B2B J2 Pin	B2B J3 Pin	Input/ Output	Note
PL_VIN	147, 149, 151, 153, 155, 157, 159	-	-	Input	module supply voltage
PS_VIN	-	154, 156, 158	-	Input	module supply voltage
PS_3.3V	-	160	-	Input	module supply voltage
VCCIO12	54, 55	-	-	Input	high range bank I/O voltage
VCCIO13	112, 113	-	-	Input	high range bank I/O voltage
VCCIO33	-	-	115, 120	Input	high performance bank I/O voltage
VCCIO34	29, 30		-	Input	high performance bank I/O voltage
VCCIO35	87, 88		-	Input	high performance bank I/O voltage
VBAT_IN	146	-	-	Input	RTC (battery-backed) supply voltage
PS_1.8V	-	130	-	Output	internal 1.8V voltage level (Process System)

Table 18: Power rails of the SoC module on B2B connectors.

6.6 Bank Voltages

7.4 Connector Speed Ratings

The connector speed rating depends on the stacking height:

Stacking height	Speed rating
4 mm, Single-Ended	13GHz/26Gbps
4 mm, Differential	13.5GHz/27Gbps
5 mm, Single-Ended	13.5GHz/27Gbps
5 mm, Differential	20GHz/40 Gbps

The SS5/ST5 series board-to-board spacing is currently available in 4mm (0.157"), 4.5mm (0.177") and 5mm (0.197") stack heights.

The data in the reports is applicable only to the 4mm and 5mm board-to-board mated connector stack height.

7.5 Manufacturer Documentation

8 Variants Currently In Production

Module Variant	Zynq SoC	SoC Junction Temperature	Operating Temperature Range
TE0745-02-30-1I	XC7Z030-1FBG676I	–40°C to +100°C	Industrial
TE0745-02-35-1C	XC7Z035-1FBG676C	0°C to +85°C	Commercial
TE0745-02-45-1C	XC7Z045-1FBG676C	0°C to +85°C	Commercial
TE0745-02-45-2I	XC7Z045-2FBG676I	–40°C to +100°C	Industrial

Table 20: Module variants.

9 Technical Specification

9.1 Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes
PL_VIN	-0.3	5	V	TI TPS720 data sheet
PS_VIN	-0.3	7	V	TI TPS82085 data sheet
PS_3.3V	3.135	3.465	V	3.3V nominal ± 5% **Attention**: PS_3.3V is directly connected to numerous on-board peripherals as supply and I/O voltage.
VBAT supply voltage	-1	6.0	V	ISL12020MIRZ data sheet
PL IO bank supply voltage for HR I/O banks (VCCO)	-0.5	3.6	V	-
PL IO bank supply voltage for HP I/O banks (VCCO)	-0.5	2.0	V	-
I/O input voltage for HR I/O banks	-0.4	VCCO_X +0.55	V	-
I/O input voltage for HP I/O banks	-0.55	VCCO_X +0.55	V	-
GT receiver (RXP/RXN) and transmitter (TXP/TXN)	-0.5	1.26	V	-
Voltage on module JTAG pins	-0.3	3.6	V	MachX02 Family data sheet
Storage temperature	-40	+85	°C	Limits of ISL12020MIRZ RTC chp.
Storage temperature without the ISL12020MIRZ	-55	+100	°C	Limits of DDR3 memory chips.

Table 21: Module absolute maximum ratings.

Assembly variants for higher storage temperature range are available on request.

9.2 Recommended Operating Conditions

Parameter	Min	Max	Units	Notes	Reference Document
PL_VIN	3.3	4.5	V	-	TI TPS720 data sheet
PS_VIN	3.3	6.0	V	-	TI TPS82085 data sheet
PS_3.3V	3.135	3.465	V	-	3.3V nominal ± 5%
VBAT_IN supply voltage	2.7	5.5	V	-	ISL12020MIRZ data sheet

Parameter	Min	Max	Units	Notes	Reference Document
PL I/O bank supply voltage for HR I/O banks (VCCO)	1.14	3.465	V	-	Xilinx datasheet DS191
PL I/O bank supply voltage for HP I/O banks (VCCO)	1.14	1.89	V	-	Xilinx datasheet DS191
I/O input voltage for HR I/O banks	-0.20	VCCO_X+ 0.20	V	-	Xilinx datasheet DS191
I/O input voltage for HP I/O banks	-0.20	VCCO_X+ 0.20	V	-	Xilinx datasheet DS191
GT receiver (RXP/RXN) and transmitter (TXP/TXN)	(*)	(*)	V	(*) Check datasheet	Xilinx datasheet DS191
Voltage on Module JTAG pins	3.135	3.6	V	JTAG signals forwarded to Zynq module config bank 0	MachX02 Family Data Sheet

Table 22: Module recommended operating conditions.

Please check Xilinx datasheet DS191 (for XC7Z030) for complete list of absolute maximum and recommended operating ratings.

9.3 Operating Temperature Ranges

Commercial grade: 0°C to +70°C.

Industrial grade: -40°C to +85°C.

Extended grade: 0°C to +85°C.

The module operating temperature range depends also on customer design and cooling solution. Please contact us for options.

9.4 Physical Dimensions

- Module size: 52 mm × 76 mm. Please download the assembly diagram for exact numbers
- Mating height with standard connectors: 4mm
- PCB thickness: 1.6mm
- Highest part on PCB: approx. 3mm. Please download the step model for exact numbers

All dimensions are given in millimeters.

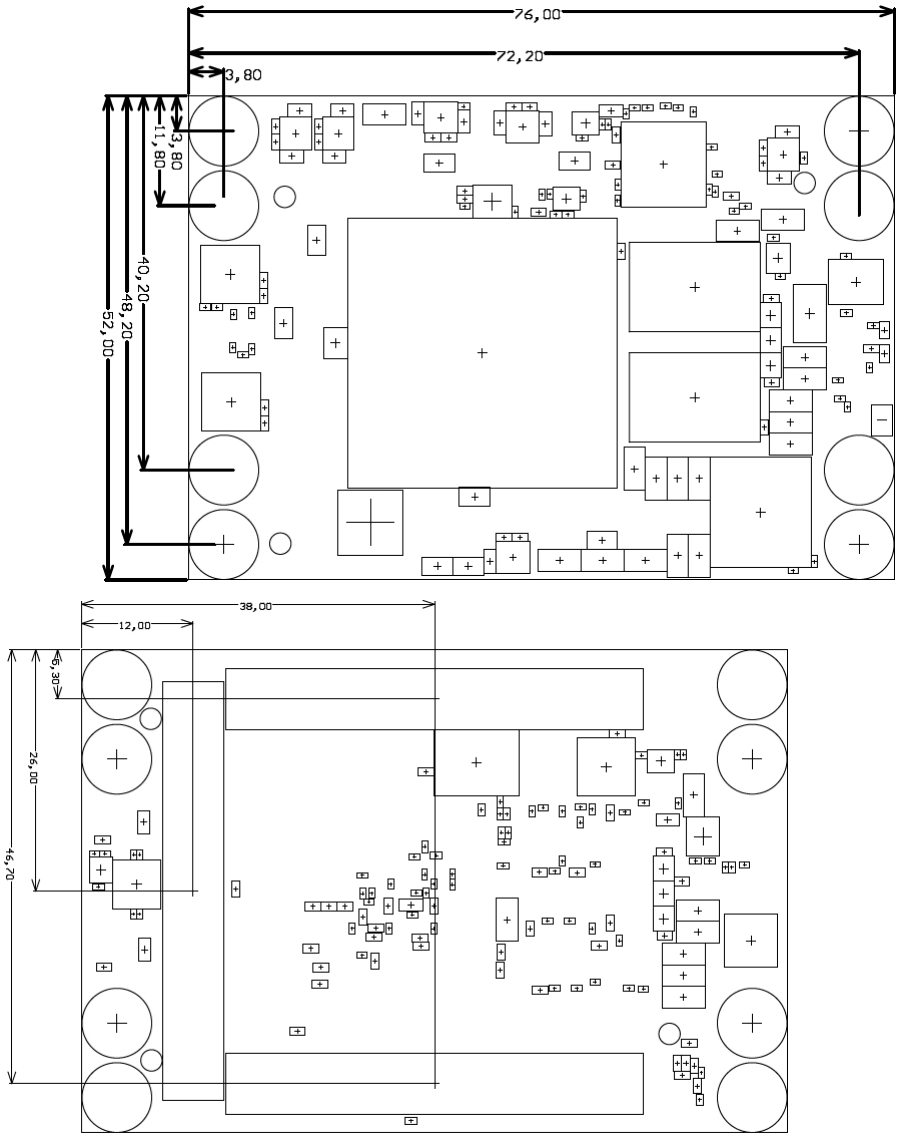

Figure 6: Physical dimensions of the TE0745 SoC module.

10 Revision History

10.1 Hardware Revision History

Date	Revision	Notes	Link to PCN	Documentation Link
2016-10-11	02	• First Production release • Refer to Changes list in Schematic for further details in changes to REV01	-	TE0745-02
2016-04-18	01	• Prototypes	-	TE0745-01

Table 23: Module hardware revision history.

Hardware revision number is written on the PCB board together with the module model number separated by the dash.

Figure 7: TE0745 module revision number.

10.2 Document Change History

Date	Revision	Contributors	Description
2017-11-14	V.80	John Hartfiel	• Update B2B Section
2017-11-13	V.79	Ali Naseri, Jan Kumann, John Hartfiel	• First TRM release

Table 24: Document change history.

RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

WEEE

Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

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